



General Description

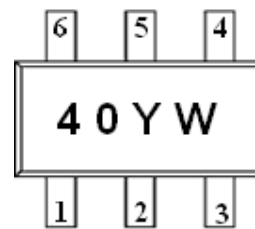
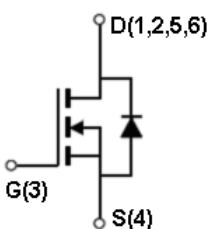
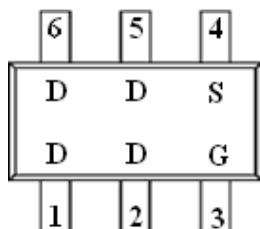
AFN1440, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- 40V/3.6A, $R_{DS(ON)} = 50m\Omega @ V_{GS} = 10V$
- 40V/2.8A, $R_{DS(ON)} = 65m\Omega @ V_{GS} = 4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-363 package design

Pin Description (SOT-363)



Application

- Load Switches
- DC/DC Converters
- Power Management
- LED Backlighting

Pin Define

Pin	Symbol	Description
1	D	Drain
2	D	Drain
3	G	Gate
4	S	Source
5	D	Drain
6	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN1440S36RG	40YW	SOT-363	Tape & Reel	3000 EA

- ※ 40 parts code
- ※ Y year code (0 ~ 9)
- ※ W week code (A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52)
- ※ AFN1440S36RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	40	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	I _D	T _A =25°C 3.6	A
		T _A =70°C 2.8	
Pulsed Drain Current	I _{DM}	7	A
Continuous Source Current(Diode Conduction)	I _S	1.3	A
Power Dissipation	P _D	T _A =25°C 1.5	W
		T _A =70°C 1.0	
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	120	°C/W

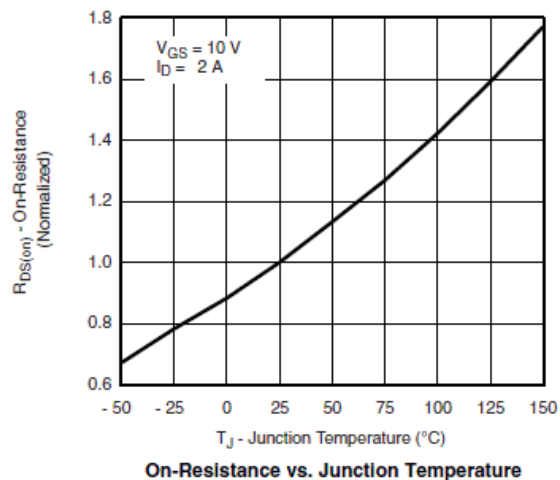
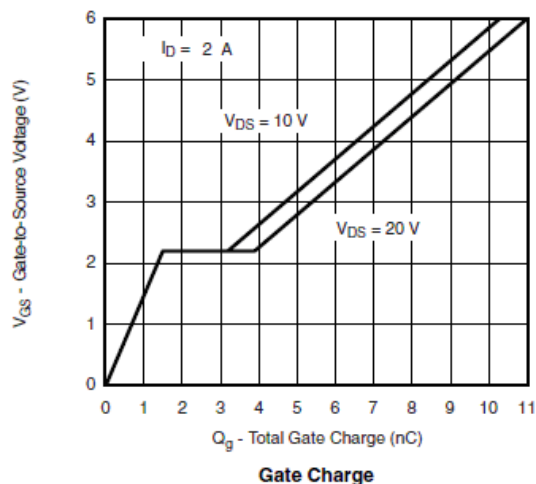
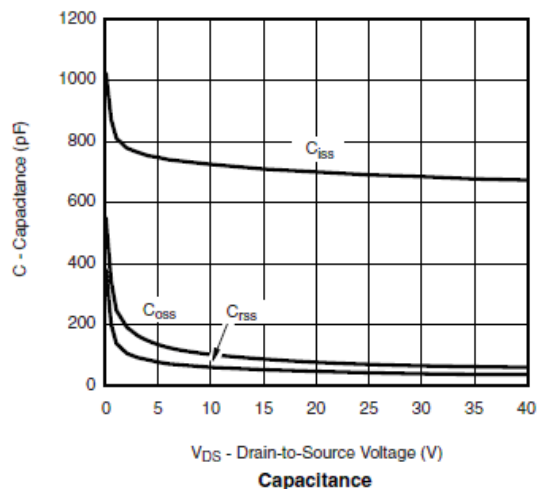
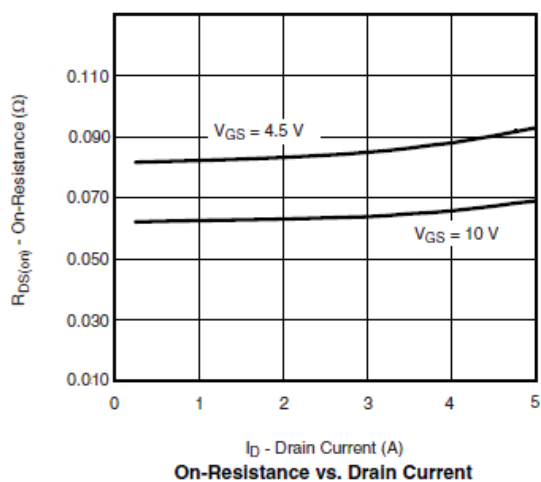
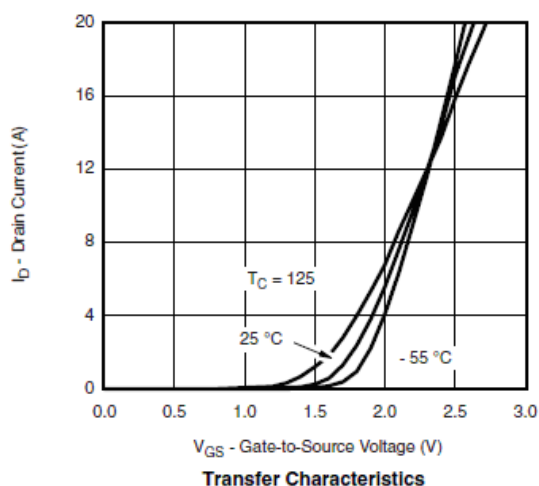
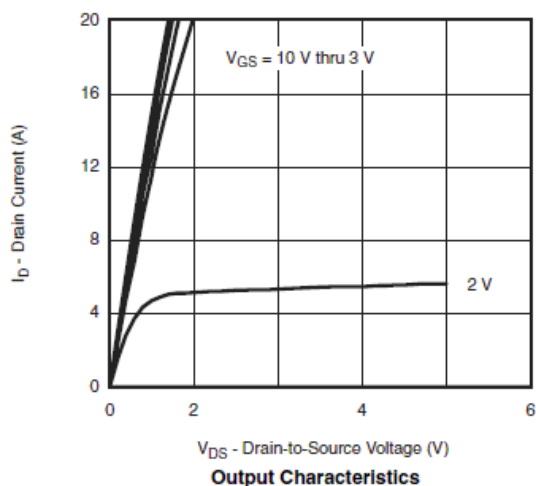
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0		2.0	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V			1	uA
		V _{DS} =40V, V _{GS} =0V T _J =85°C			10	
On-State Drain Current	I _{D(on)}	V _{DS} ≥ 5V, V _{GS} =10V	10			A
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =3.6A		40	50	mΩ
		V _{GS} =4.5V, I _D =2.8A		50	65	
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =2.0A		16		S
Diode Forward Voltage	V _{SD}	I _S =1.5A, V _{GS} =0V		0.85	1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =20V, V _{GS} =4.5V I _D ≡2A		10	15	nC
Gate-Source Charge	Q _{gs}			2		
Gate-Drain Charge	Q _{gd}			2.5		
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V f=1MHz		650		pF
Output Capacitance	C _{oss}			75		
Reverse Transfer Capacitance	C _{rss}			45		
Turn-On Time	t _{d(on)}	V _{DD} =15V, R _L =15Ω I _D ≡1A, V _{GEN} =10V R _G =6Ω		8	15	ns
	t _r			12	20	
Turn-Off Time	t _{d(off)}			28	40	
	t _f			8	15	

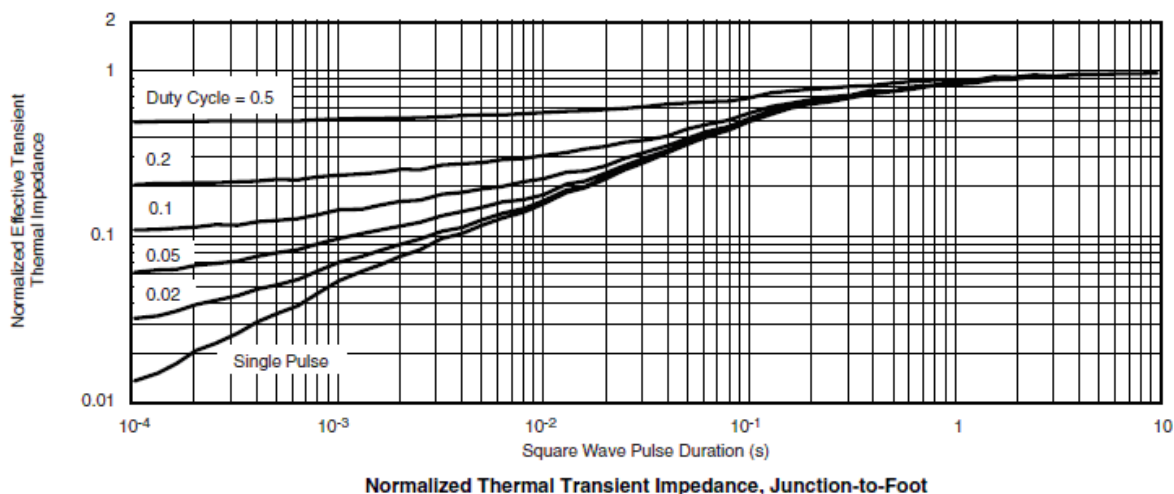
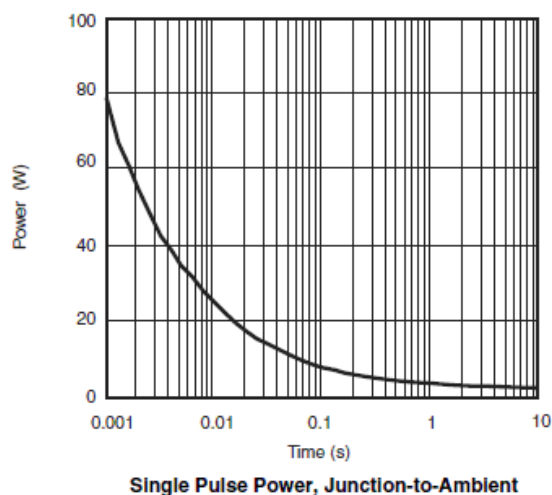
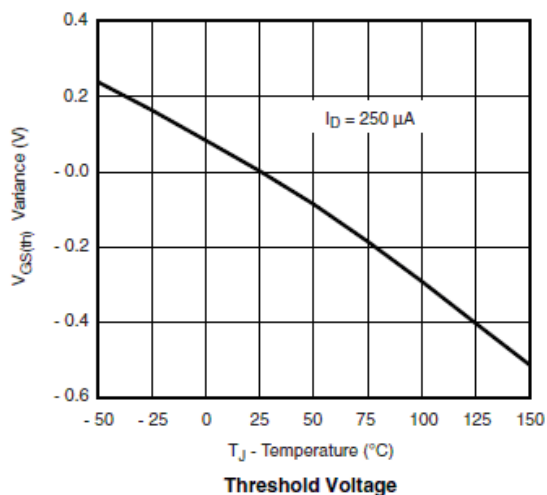
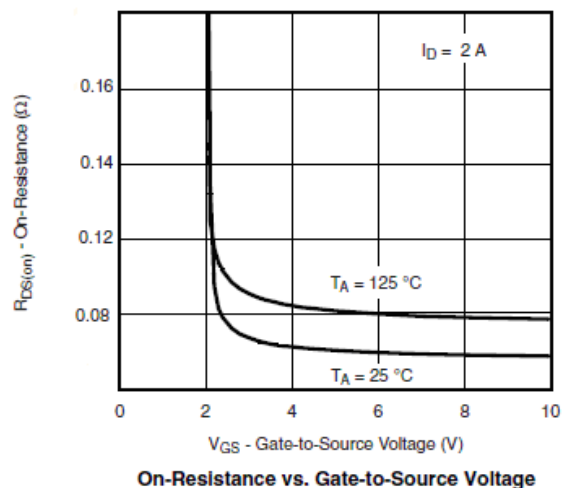
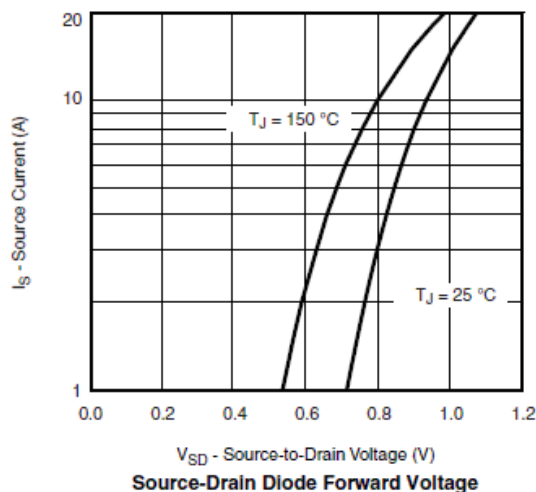


Typical Characteristics





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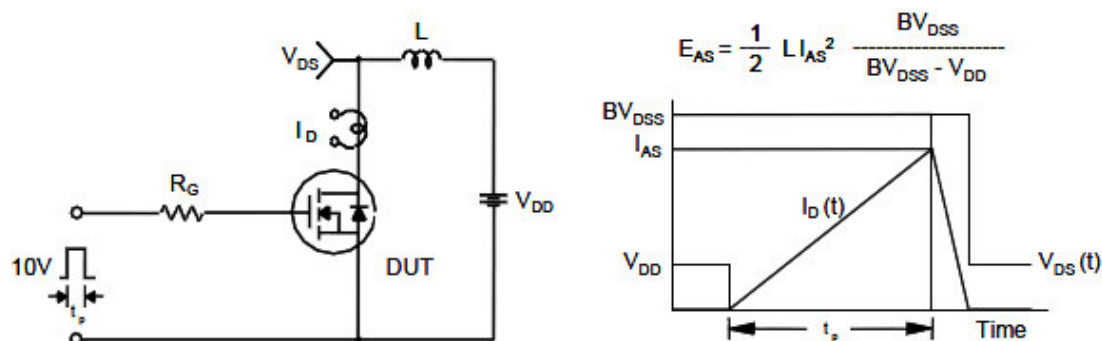
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

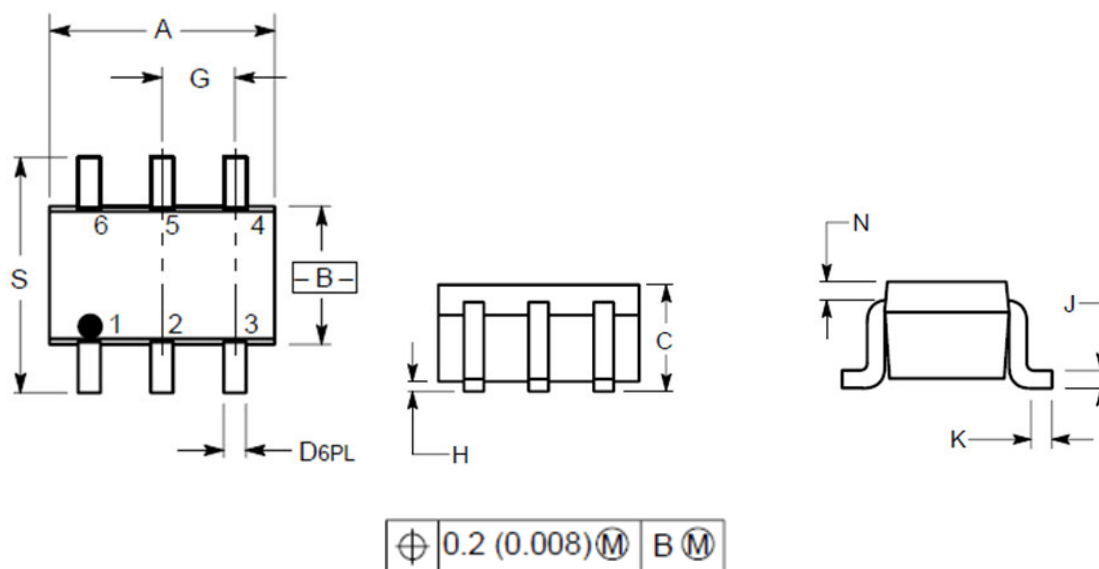


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (SOT-363)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

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